# **MA6X123** (MA123)

## Silicon epitaxial planar type

#### For switching circuit

#### ■ Features

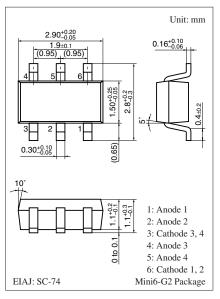
- Four isolated elements contained in one package, allowing highdensity mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t<sub>rr</sub>
- Small terminal capacitance C<sub>t</sub>

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current *1	$I_F$	100	mA
Peak forward current *1	$I_{FM}$	225	mA
Non-repetitive peak forward surge current *1, 2	$I_{FSM}$	500	mA
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

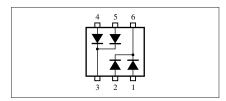
Note) \*1: Value for single diode

\*2: t = 1 s



Marking Symbol: M2B

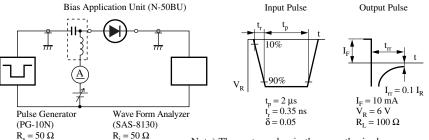
#### Internal Connection



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

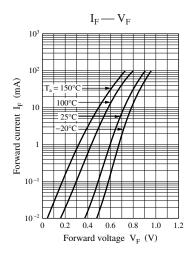
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu A$	80			V
Reverse current	$I_R$	V <sub>R</sub> = 75 V			100	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			2	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

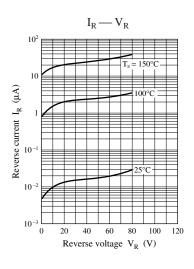
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. Absolute frequency of input and output is 100 MHz.
  - 3. \*: t<sub>rr</sub> measurement circuit

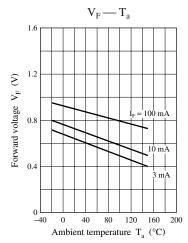


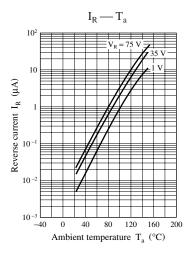
Note) The part number in the parenthesis shows conventional part number.

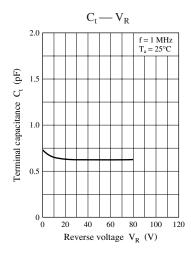
MA6X123 Panasonic

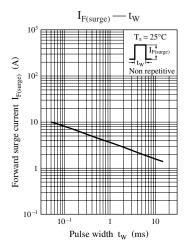












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